Fourth Quarter FY 2017 Quarterly Update

Infineon Technologies AG
Investor Relations

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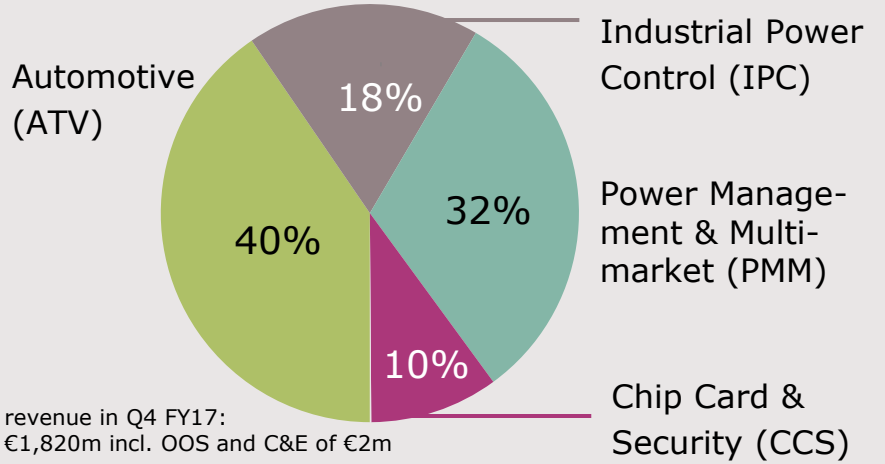
Please regard the slides "Disclaimer", "Notes" and "Glossary" at the end of the presentation.

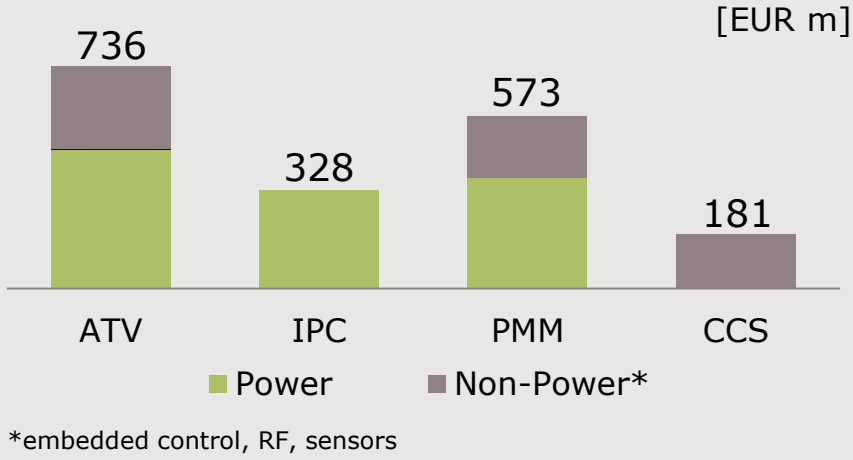
Infineon at a glance

Business Segments



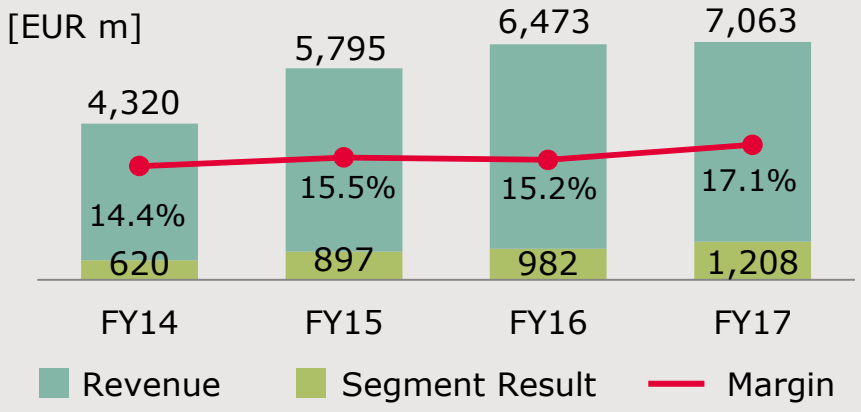
revenue in Q4 FY17:
€1,820m incl. OOS and C&E of €2m

Power represents ~60% of revenue



*embedded control, RF, sensors

Financials



Market Position

Automotive	Power	Smart card ICs
		
# 2	**# 1**	**# 1**
Strategy Analytics, April 2017	IHS Markit, Technology Group, August 2017	IHS Markit, Technology Group, July 2017

Our strategy is targeted at value creation through sustainable organic growth

Focus	Technology leadership		System understanding
Automotive	**Power mgmt**	**RF and sensors**	**Security**
System leader in automotive	#1; system and technology leader	Broad RF and sensor technology portfolio	#1 in security solutions

Average-cycle financial targets

~8% p.a.	~17%	~13%
revenue growth	Segment Result Margin	investment-to-sales (*thereof capex*: ~11%*)

Continued value creation for shareholders

Organic RoCE ~ 2x WACC

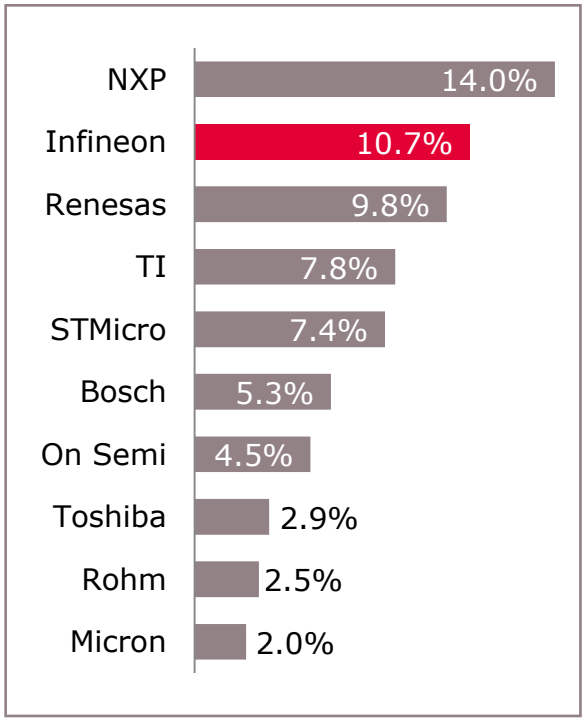
- paying out at least a constant dividend even in periods of slower growth
- continuous EPS increase

* Infineon reports under IFRS and has therefore to capitalize development assets which represents currently ~2% of sales.

Infineon increased relative market share in power and outperformed chip card market

Automotive semiconductors

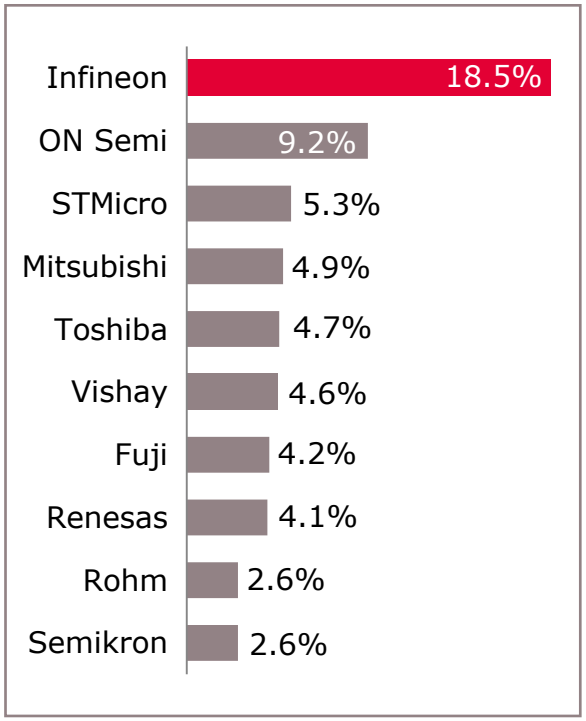
total market in 2016: $30.2bn



Source: Strategy Analytics, "2016 Automotive Semiconductor Vendor Share", April 2017

Power discretes and modules

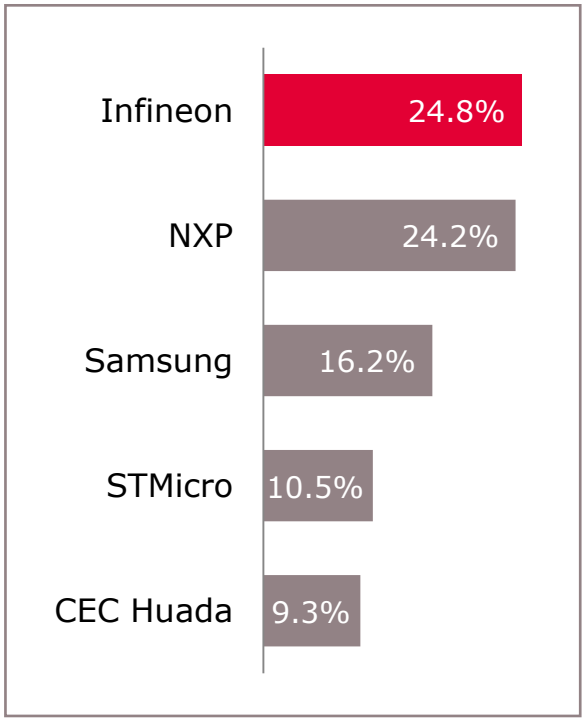
total market in 2016: $15.9bn



Source: Based on or includes content supplied by IHS Markit, Technology Group, "Power Semiconductor Annual Market Share Report", August 2017

microcontroller-based Smart Card ICs

total market in 2016: $2.79bn



Source: Based on or includes content supplied by IHS Markit, Technology Group, "Smart Cards Semiconductors Report", July 2017

Tight customer relationships are based on system know-how and app understanding

ATV

Autoliv, BOSCH, Continental, BYD, DELPHI, HELLA, DENSO, HYUNDAI, HITACHI Inspire the Next, LEAR CORPORATION, KEIHIN, Mando, MITSUBISHI ELECTRIC, preh, OMRON, Valeo, ZF

IPC

ABB, ALSTOM, BOMBARDIER, Danfoss, 中国中车 CRRC, EMERSON, EATON, Midea, GOLDWIND, Rockwell Automation, Schneider Electric, SIEMENS, SUNGROW, TOSHIBA, YASKAWA, Vestas

PMM

ARTESYN EMBEDDED TECHNOLOGIES, CISCO, BOEING, DELL, DELTA, ERICSSON, Hewlett Packard Enterprise, HUAWEI, Lenovo, LG, LITEON, OSRAM, NOKIA, Quanta Computer, Panasonic, ZTE, SAMSUNG

CCS

gemalto security to be free, GPO, IDEMIA augmented identity, hp, Lenovo, Microsoft, SAMSUNG, Watchdata

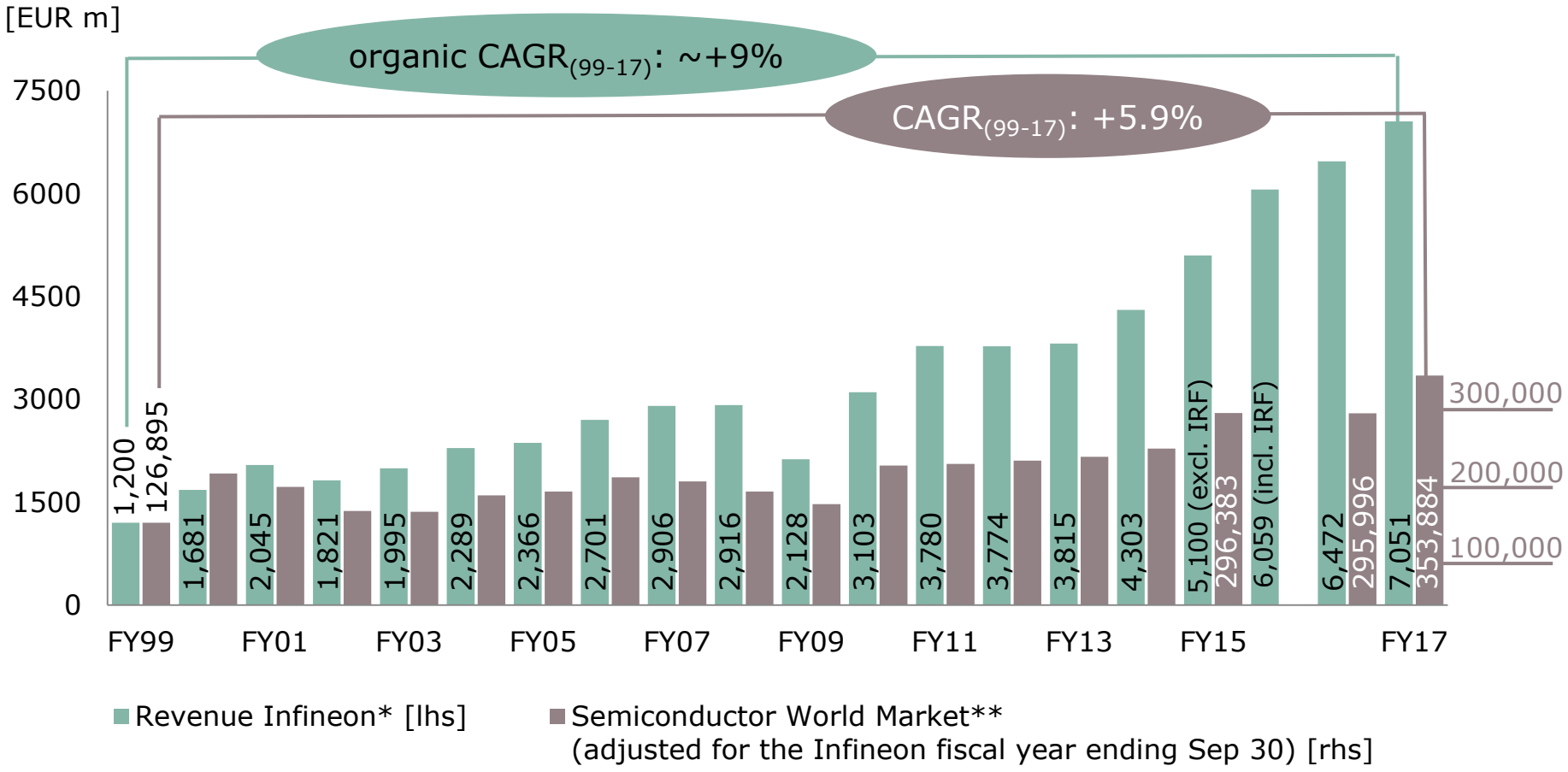
EMS partners

flex, FOXCONN

Distribution partners

arrow, AVNET Reach Further, intron 英恒, JCET 晶川电子, MACNICA, NEXTY Electronics Corporation, RUTRONIK ELECTRONICS WORLDWIDE, SAC, 威健 WEIKENG

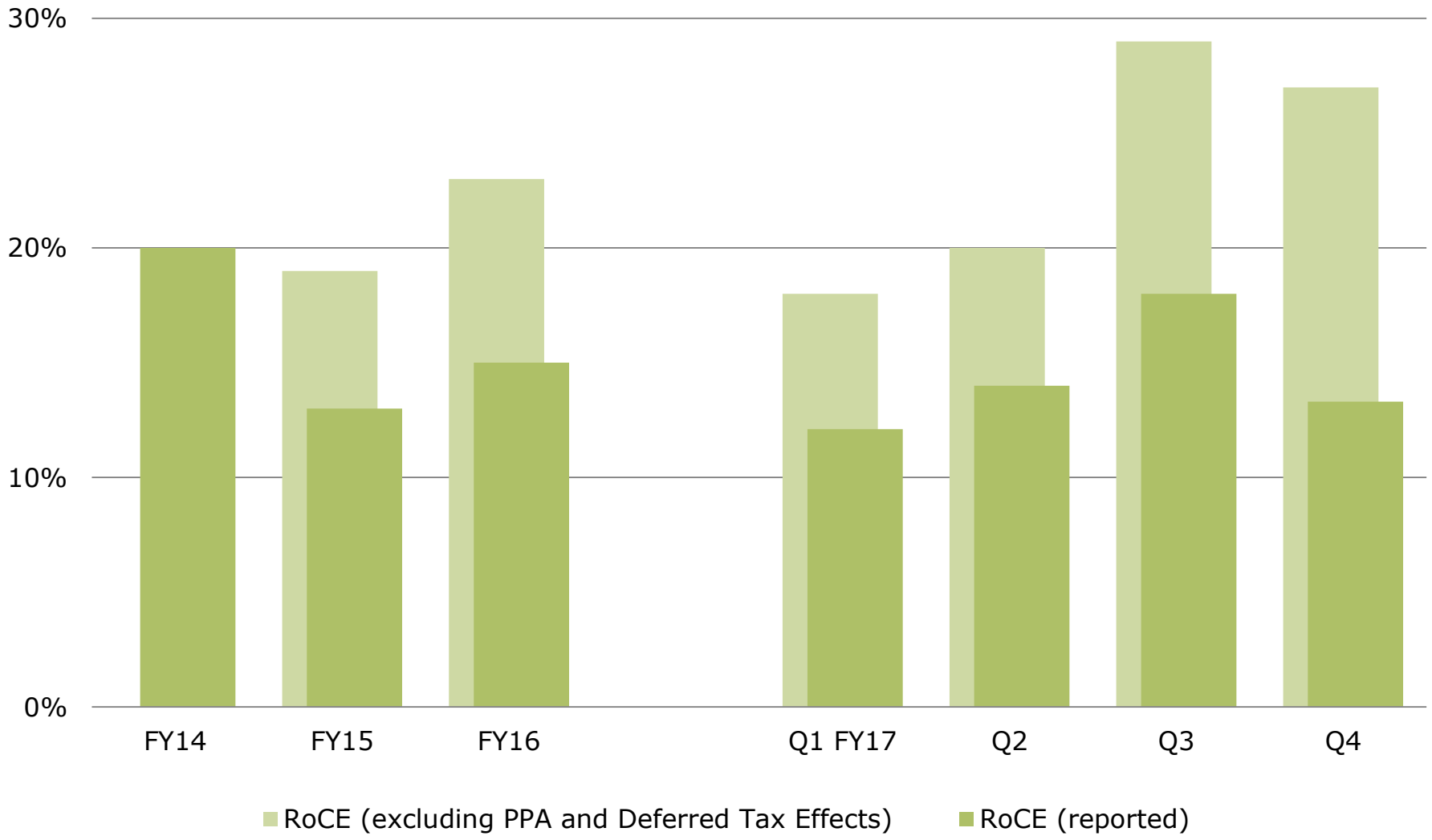
Infineon's organic revenue development clearly outperformed total semi market



* Based on Infineon's portfolio (excl. Other Operating Segments and Corporate & Eliminations) per end of FY17.

** Source: WSTS (World Semiconductor Trade Statistics) in EUR, October 2017

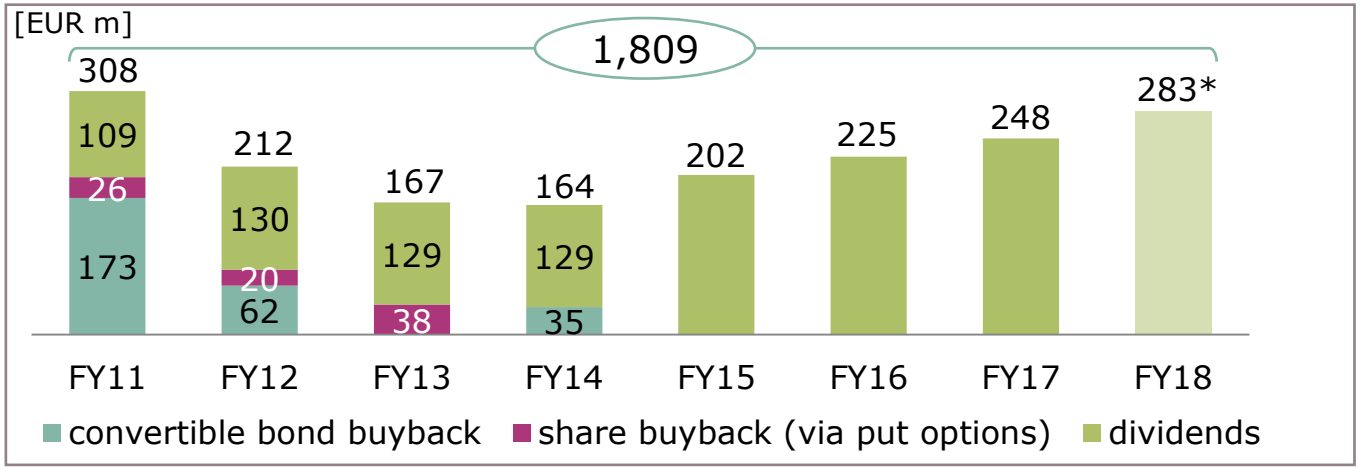
Organic RoCE as the key value metric typically amounts to ~2x WACC



Our commitment to investors: Continued value creation through growth

Earnings-per-share (EPS) development

Total cash return to shareholders



- Policy of sustainable dividend payout
- Increase of dividend from €0.22 to €0.25*
- Payment of €283m*

* Proposal to the AGM to be held on 22 February 2018

Outlook for Q1 FY18 and FY18

	Outlook Q1 FY18*	Outlook FY18* (compared to FY17)
Revenue	Decrease of 2% +/- 2%-points	Increase of 9% +/- 2%-points
Segment Result Margin	At the mid-point of the revenue guidance: ~15%	At the mid-point of the revenue guidance: ~17%
Investments in FY18		€1.1bn to €1.2bn
D&A in FY18		About €880m**

* Based on an assumed average exchange rate of $1.15 for €1.00.

** Including D&A on tangible and intangible assets from purchase price allocation of International Rectifier.

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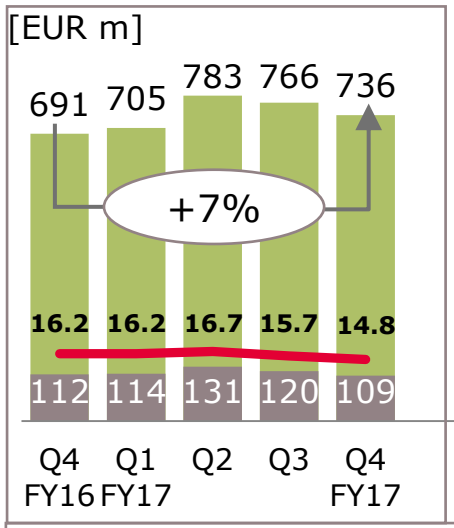
Q4 FY17 Group and Division Performance

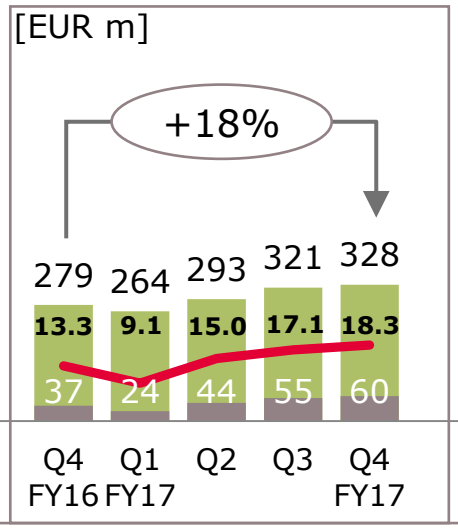
IFX	Revenue: €1,820m (+9% y-y)	Segment Result: €328m (+17% y-y)	Segment Result Margin: 18.0%

ATV



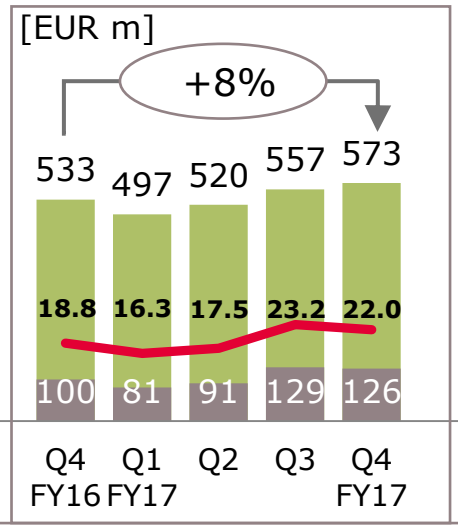
- Q4 FY17: q-q revenue decline mainly due to weaker US dollar
- Revenue increased in xEV and ADAS

IPC



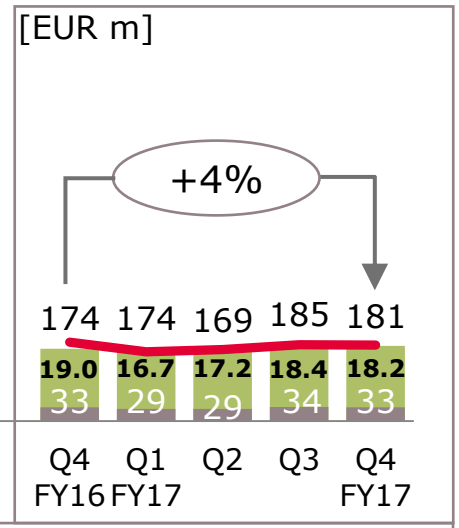
- Q4 FY17: q-q revenue increase driven by wind, drives, traction and home appliances

PMM



- Q4 FY17: q-q revenue increase driven by seasonal demand in mobile devices

CCS



- Q4 FY17: q-q revenue decline mainly due to weaker US dollar

Revenue | Segment Result | Segment Result Margin in %

Last major step in completing IRF integration: fab in Newport (Wales) sold to Neptune 6 Ltd.

Background: IR Newport Ltd.

- **01/2015:** Acquired as part of International Rectifier
- **04/2015:** Announcement to either close or sell the fab by the end of CY 2017
- **09/2017:** Signing of definitive agreement and handover to new owner

Key facts

- Fab handed over on 29 September 2017
- Infineon and Neptune 6 have entered into a 2-years wafer supply agreement

Strategic rationale

- Economies of scale not competitive within Infineon's manufacturing landscape
- Supply agreement ensures a mutually smooth transition phase for seller and buyer

Financial impact

- Short-term: negligible impact; avoidance of negative one-time effects from closure
- Mid-/long-term: increasingly positive effects from improved cost position

Major design-win achieved for µC AURIX™ 2G of several hundred million Euros over lifetime

AURIX™ 2G key features

- performance: supported by hard-coded algorithms
- power consumption
- scalability: wide range of eFlash configurations
- functional safety: ASIL-D compliant
- security features: integrated HSM

Platforms addressed by the design-win

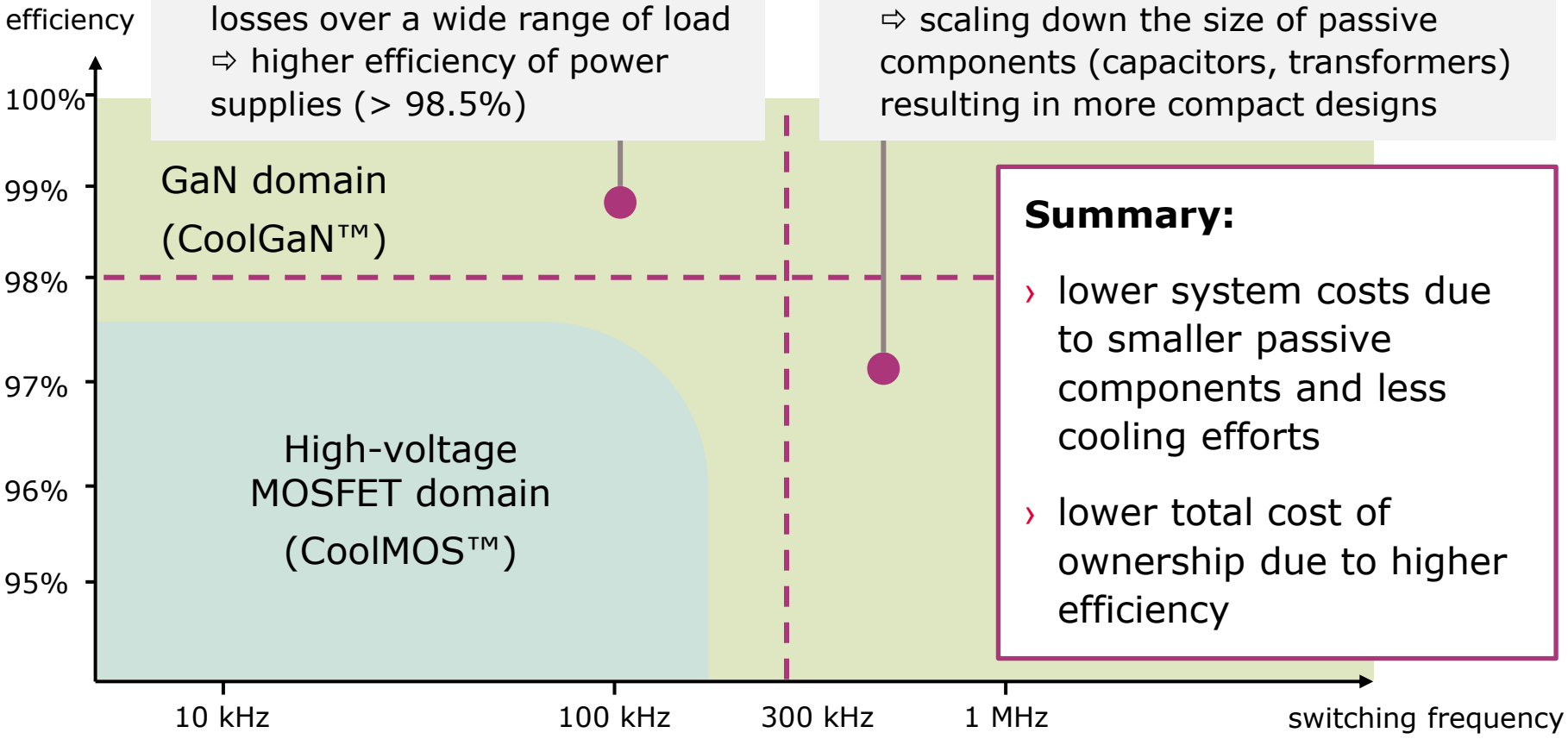
- powertrain
  - ICE transmission
  - xEV motor control
- chassis
- traditional safety
  - braking
  - airbag
- high-growth ADAS
  - camera
  - radar
  - sensor fusion

Material-specific advantages of gallium nitride (GaN)-based HEMTs vs silicon-based MOSFETs

CoolGaN™ vs CoolMOS™ positioning

Initial use case #1:
› lower switching and on-state losses over a wide range of load ⇨ higher efficiency of power supplies (> 98.5%)

Initial use case #2:
› higher switching frequency (> 300 kHz) ⇨ scaling down the size of passive components (capacitors, transformers) resulting in more compact designs



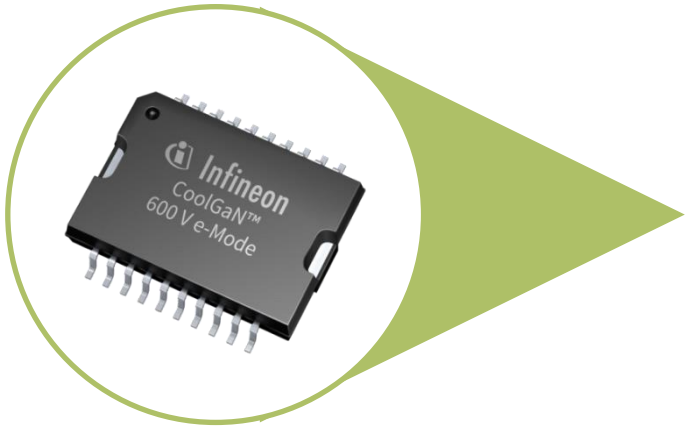
Summary:

› lower system costs due to smaller passive components and less cooling efforts

› lower total cost of ownership due to higher efficiency

Infineon launched first GaN-based product: game-changing 600 V CoolGaN™ power switch

600 V CoolGaN™ selected by Eltek for Flatpack2 SHE (super high-efficient)
3 kW AC-DC power conversion module for data center and telecom applications



ELTEK
A Delta Group Company

Flatpack2 SHE


data center


base stations


telecom central office

CoolGaN™ target applications to come

- consumer: power supply for super-thin flat panel TVs
- mobile devices: ultra-compact adapters and chargers

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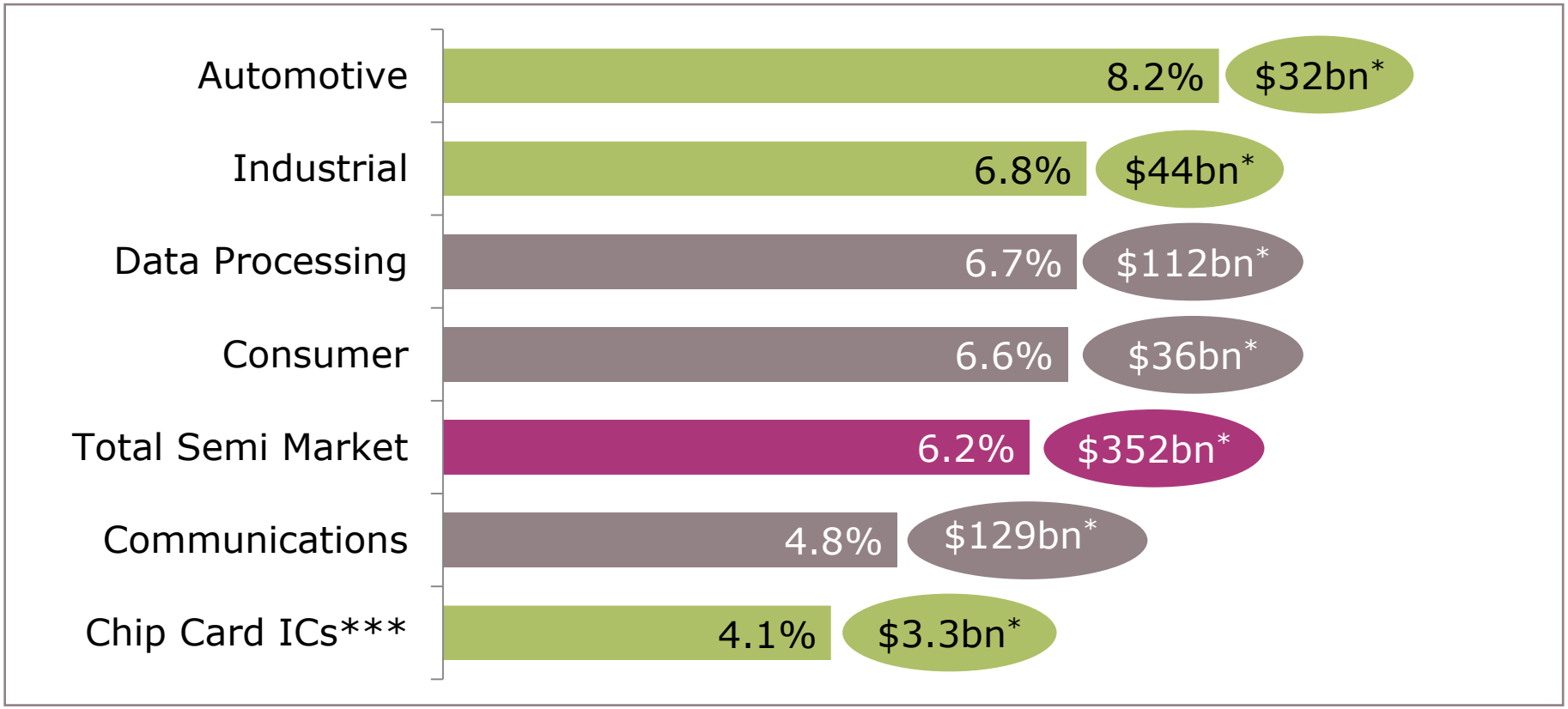
Reference to web presentations

10 Oct 2017:	ATV Division Call by Peter Schiefer, Division President Automotive www.infineon.com/atv-call
29 Jun 2017:	PMM Division Call by Andreas Urschitz Division President Power Management & Multimarket www.infineon.com/pmm-call
11 May 2017:	Deutsche Bank AutoTech Conference by Dr. Jürgen Rebel, CVP Investor Relations www.infineon.com/db-autotech
16 Mar 2017:	Bernstein xEV and Energy Storage Conference by Hans Adlkofer, VP Automotive System Group www.infineon.com/bernstein

Infineon benefits from industrial and auto, the by far fastest growing segments

CAGR 2016 – 2021** by Semiconductor Industry Segment



* Market size in calendar year 2016

** Source: Based on or includes content supplied by IHS Markit, Technology Group, "Worldwide Semiconductor Shipment Forecast", September 2017

*** Source: ABI Research, "Secure Smart Card & Embedded Security IC Technologies", August 2017; microcontroller ICs

Infineon is system leader in automotive; making cars clean, safe and smart

#2 with market share gains in power and sensors:
- #1 in power semiconductors*
- #2 in sensors*
- #4 in microcontrollers* (#1 in powertrain**)

Most balanced portfolio with sensors, micro-controllers and power for system approach

Leader in electric drivetrain and CO_2 reduction
- making cars clean

Leader in ADAS
- making autonomous driving safe and reliable

Leading product portfolio of sensors and security ICs for individual convenience and connectivity
- making cars smart

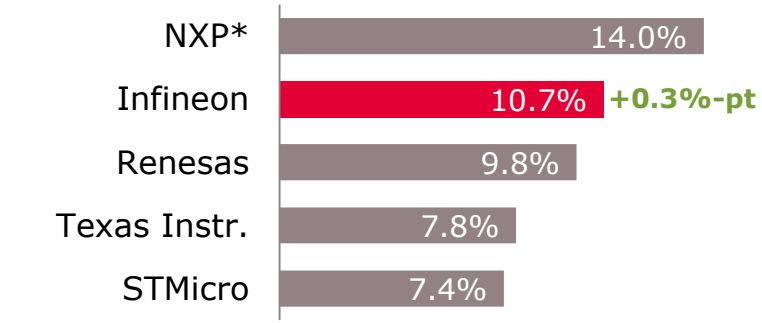
Focus on sustainable high-bill-of-material areas: powertrain, safety/ADAS/autonomous cars, body

Infineon is ideally positioned to benefit from ADAS/AD, xEV, connected cars and to gain further market share in Automotive

* Source: Strategy Analytics, April 2017; ** Infineon estimate.

Infineon's position in the automotive semiconductor universe

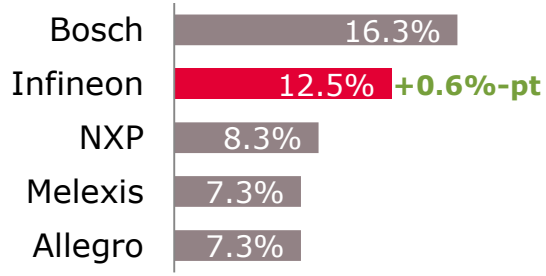
Automotive semiconductors
2016 total market size: $30.2bn



Market share trend

- Infineon benefits disproportionately from the two mega trends
  - clean cars
  - ADAS/AD

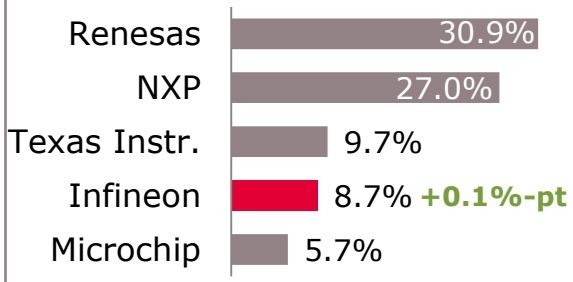
Sensors



m.s. trend

- 24 / 77 GHz radar
- REAL3™ ToF sensor

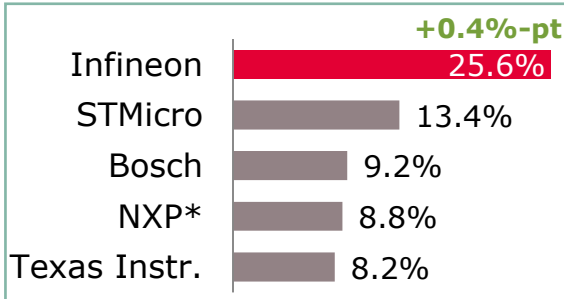
Microcontrollers



m.s. trend

- ADAS/AD
- Powertrain

Power



m.s. trend

- xEV penetration
- EPS
- Lighting

* Divestiture of NXP's Standard Product business ("Nexperia") closed on 16 Feb 2017; hence included in the 2016 ranking.
Source: Strategy Analytics, "Automotive Semiconductor Vendor Market Shares", April 2017

Megatrends shaping the automotive market; significantly increasing semi content per car

Enabling safety towards Vision Zero

Enabling CO_2 reduction

Enabling the communication of cars

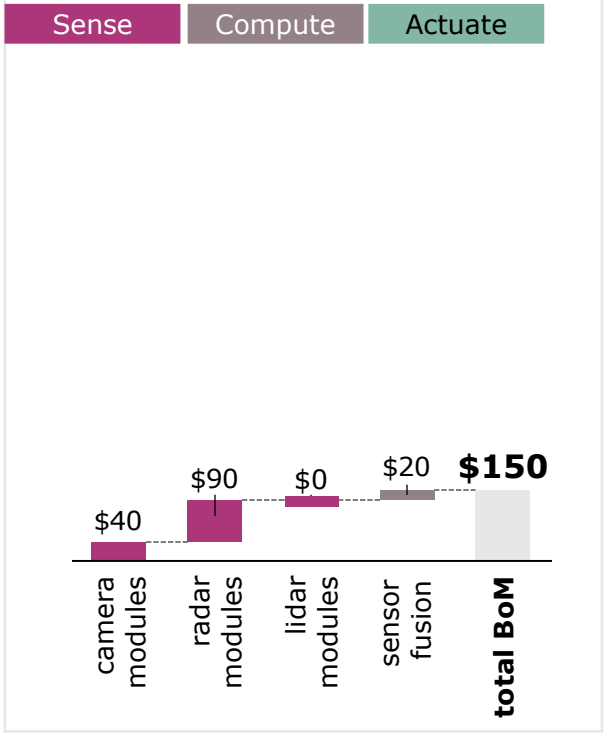
Enabling security in connected cars

ADAS/AD and clean cars will generate half of the 8% trendline growth of ATV

ADAS/AD semi growth driven by radar and camera sensor modules over the next 5 years

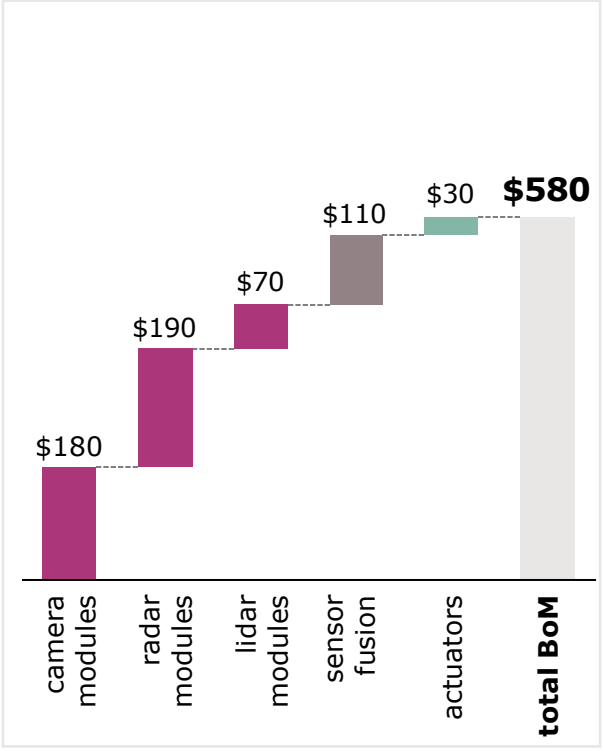
Average semiconductor content per car by level of automation

Level 2 (~2020)



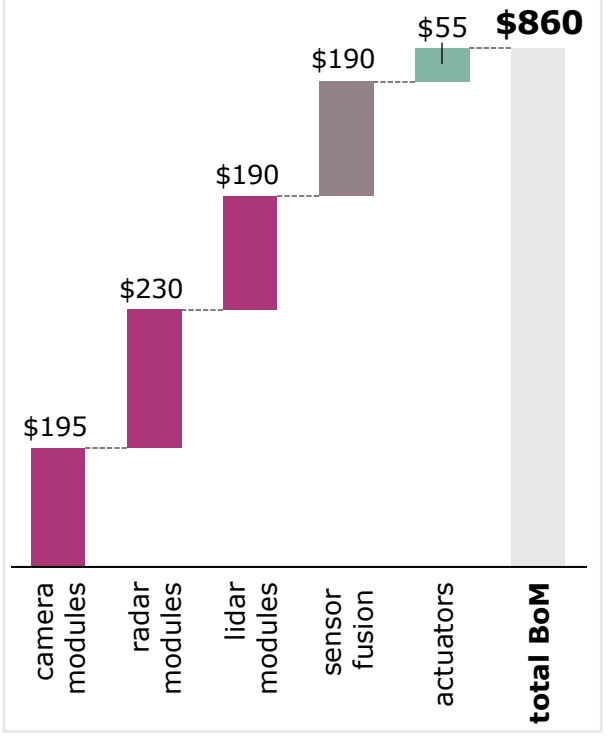
L2 vehicles in 2020:~8m

Level 3 (~2025)



L3 vehicles in 2025: ~3m

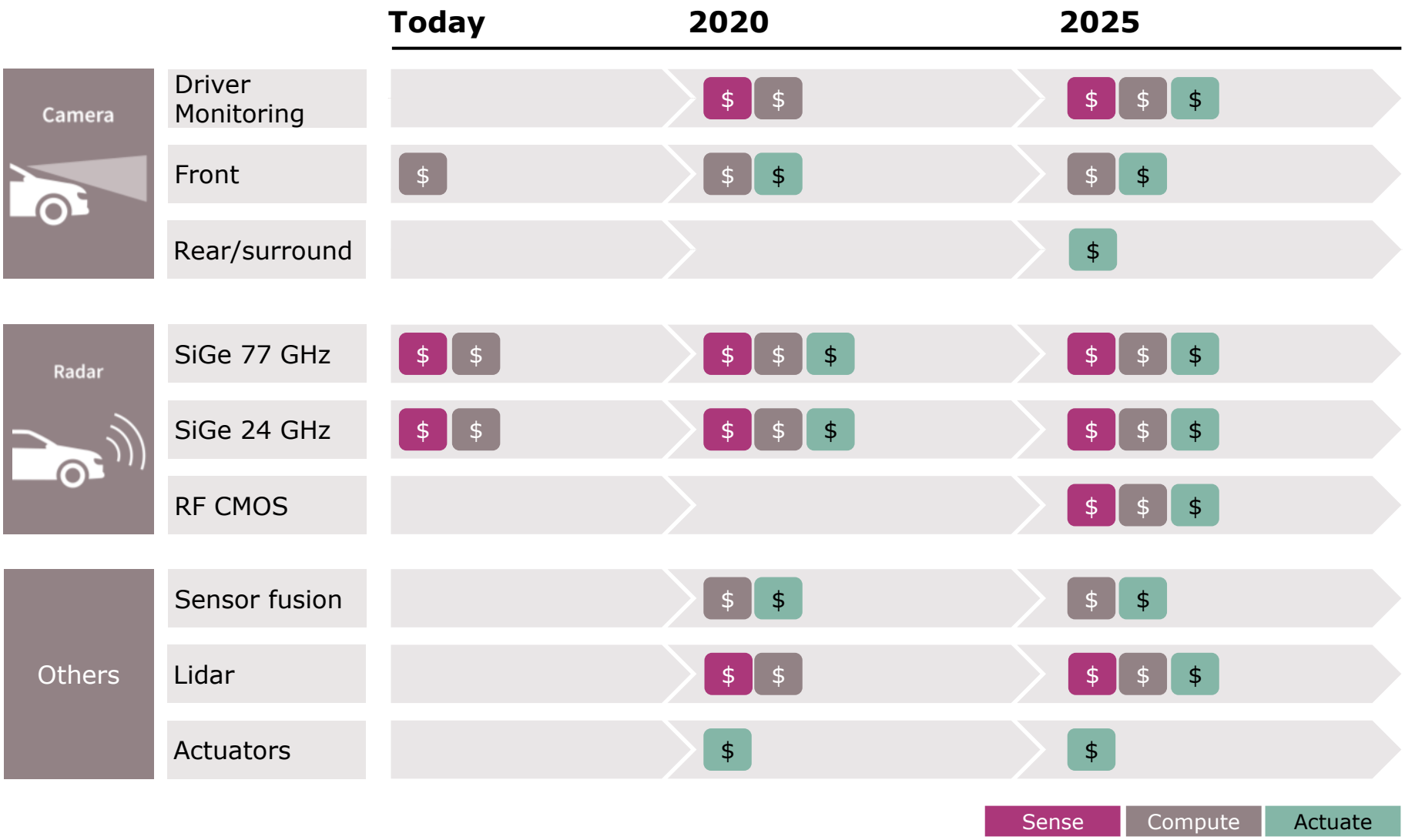
Level 4/5 (~2030)



L4/L5 vehicles in 2030: ~4m

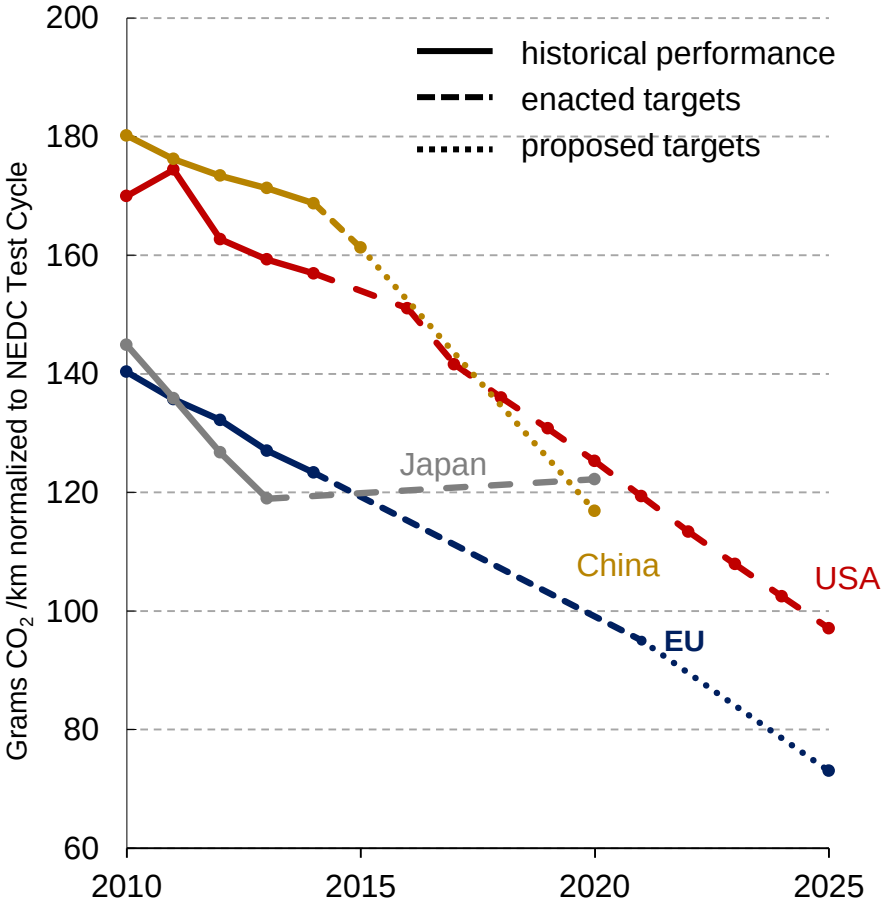
Source: Strategy Analytics; Infineon.
Bill of material contains all type of semiconductors (e.g. radar modules include µC).

Infineon's product portfolio fosters revenue growth in ADAS/AD for the next decade



CO_2 emission targets are the key triggering points for increase in semiconductors

National fleet emissions



Source: The International Council for Clean Transportation, 2017

CO_2 drives three major trends

(1) Higher efficiency of the 'classic' ICE:

- EPS (electric power steering)
- start-stop
- dual-clutch
- alternator

(2) Energy efficiency of body applications:

- power distribution
- electric motors for pumps and fans

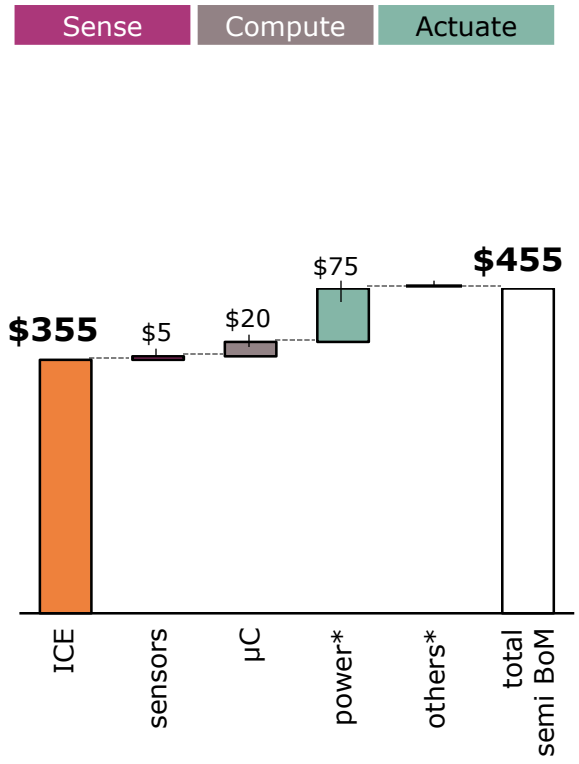
(3) Electrification of the drivetrain:

- main inverter
- auxiliary inverter
- onboard charger
- battery management

The incremental demand of power semi-conductors is a significant opportunity

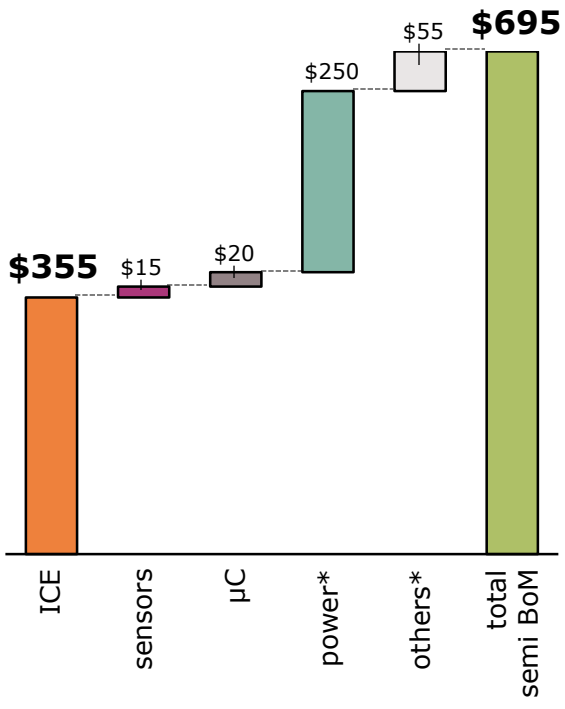
2017 average xEV semiconductor content by degree of electrification

48 V / MHEV



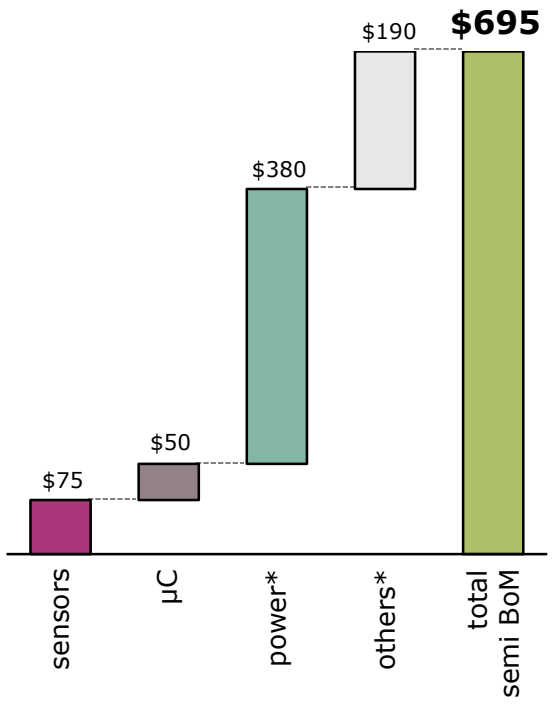
48 V / MHEV veh. in 2025: ~15m

HEV / PHEV



PHEV vehicles in 2025: ~9m

BEV



BEV vehicles in 2025: ~6m

Source: Strategy Analytics, "Automotive Semiconductor Content", May 2017; Infineon
* "power" includes linear and ASIC; "others" include opto, small signal discrete, memory

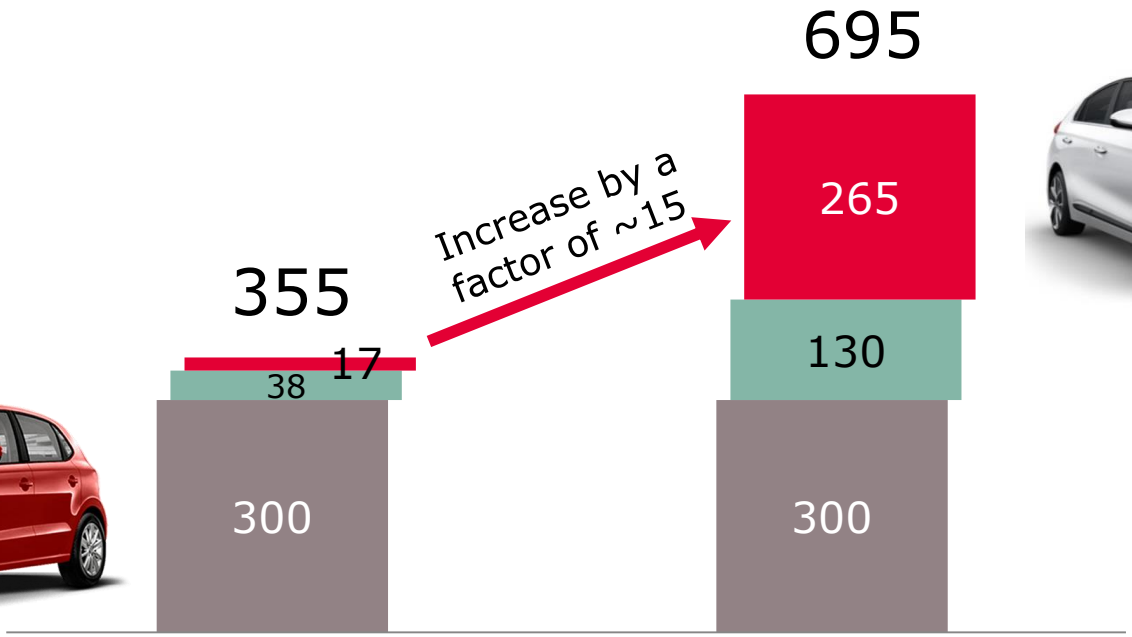
With the transition from ICE to xEV the power semi content in powertrain increases by ~15x

Average semiconductor content by type of car

[USD]

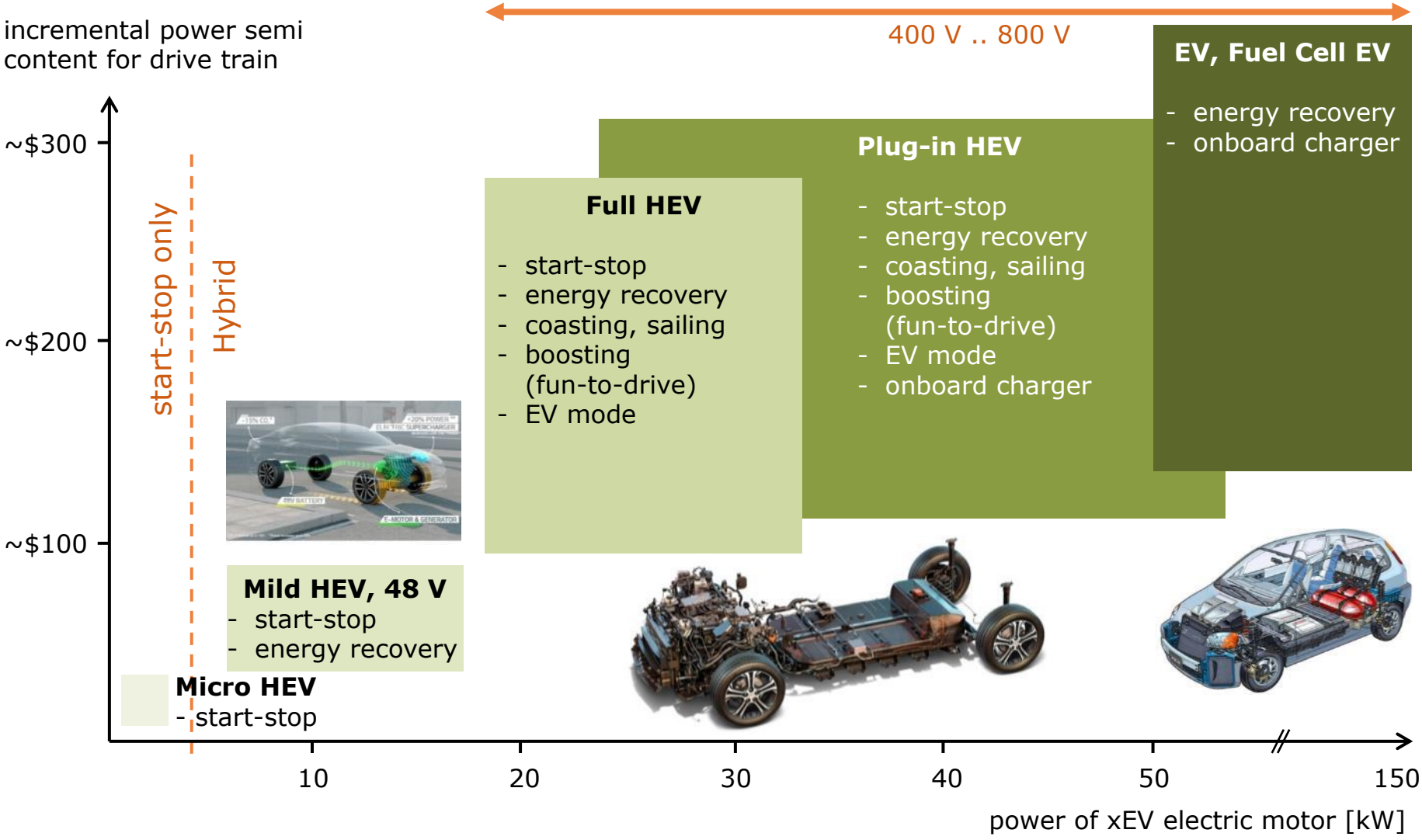
Courtesy: Volkswagen

Courtesy: Hyundai

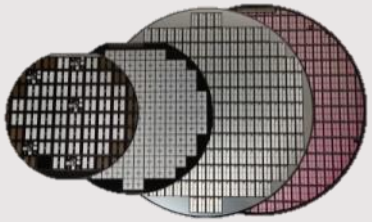
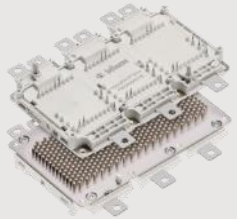
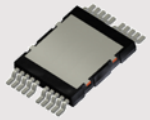
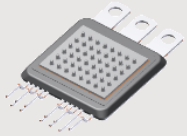
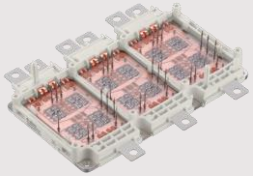


Source: Strategy Analytics, "Automotive Semiconductor Content", May 2017; Infineon

Power semiconductor demand for different levels of electrification



Infineon has all elements and unparalleled package expertise for all xEV applications

Bare die	Discretes	Scalable products	Plug-n-Play
 Si bare dies	 Si IGBT	  HybridPACK™ Double-Sided Cooling	 HybridPACK™ solutions  Easy modules
 SiC bare dies	 SiC MOSFET	    SiC optimized package solution	

ADAS/AD, clean cars, and adoption of premium features drive growth

Vehicle production	Drivers for semiconductor content per car		
	Clean cars	ADAS/AD	Comfort, premium
			

› 2% growth p.a.	› Legislation
	› Improvements of ICE
	› Higher efficiency of all electric consumers
	› Adoption of xEV
		› Today:
		  › crash avoidance
		  › ADAS
		› Tomorrow:
		  › Autonomous Driving
			› Premium cars are early adopters of high-end comfort and safety features
			› Trickling down to mid-range

~8% p.a. through-cycle growth

Infineon is #1 and technology leader in power semiconductors

#1 in the market* for MOSFETs, discrete IGBTs, IGBT-based modules and total market

Broad product and technology portfolio

Addressing broadest range of applications

Key areas of innovation

- 300 mm thin-wafer manufacturing for power semiconductors
- System leader with digitalization of the control loop and functional integration
- Leader in next-generation power semiconductor materials SiC and GaN

Infineon is ideally positioned to gain further market share and earn superior margins in power semiconductors

* Source: IHS Markit, Technology Group, "Power Semiconductor Annual Market Share Report", August 2017

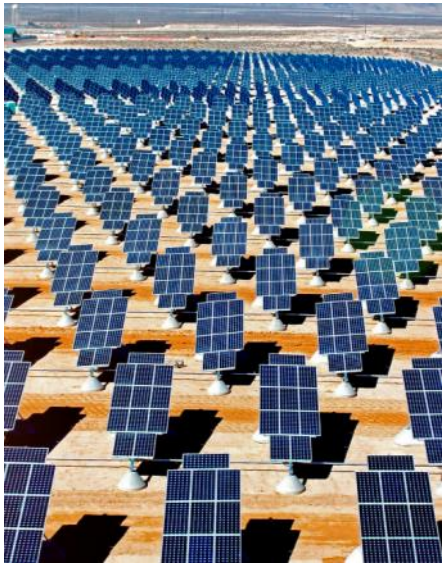
Efficiency, productivity and legislation are main market drivers for power applications

IPC

Drives

- Energy efficiency
- Automation
- Productivity increase

Renewables



- Legislation
- Growing share of renewables as part of the energy generation mix

MHA

- Energy efficiency
- Growing VSD penetration

Traction

- Growing population in mega cities
- Fast and efficient mass transport system

IPC is perfectly positioned to outperform traditional markets and leverage emerging ones

Traditional markets with <5% p.a.

- Portfolio for **automation application** to **compensate low demand** in **drives**
- **Strong** position in stable **wind market**
- Broad traction portfolio enables **compensation of low demand in high-speed trains** through urban transportation
- **Weakest level** of growth in **oil & gas** (process automation) **passed** as capex slowly recovers



+

Emerging markets with >5% p.a.

- Comprehensive offering and expertise enable **growth in SiC above average**
- Ongoing **inverterization of home appliances** enables strong growth
- Optimal position to strongly benefit from **high growth rates** in **PV**, **transmission & distribution** and **commercial, construction and agricultural vehicles**
- Emerging applications like **energy storage**, **EV charging** and **robotics** offer additional growth potential



Industrial Power Control to grow ~8% p.a.

PMM's growth is built on many applications from different sectors

PMM

Computing

- Server
- PC
- Notebook
- Peripherals

Industrial

- Industrial power supplies
- xEV charger
- PV roof-top inverter
- DIY power tools
- Lighting

Consumer / Misc

- Pedelecs / eBikes
- Multicopter
- Aviation
- Space
- Oil exploration

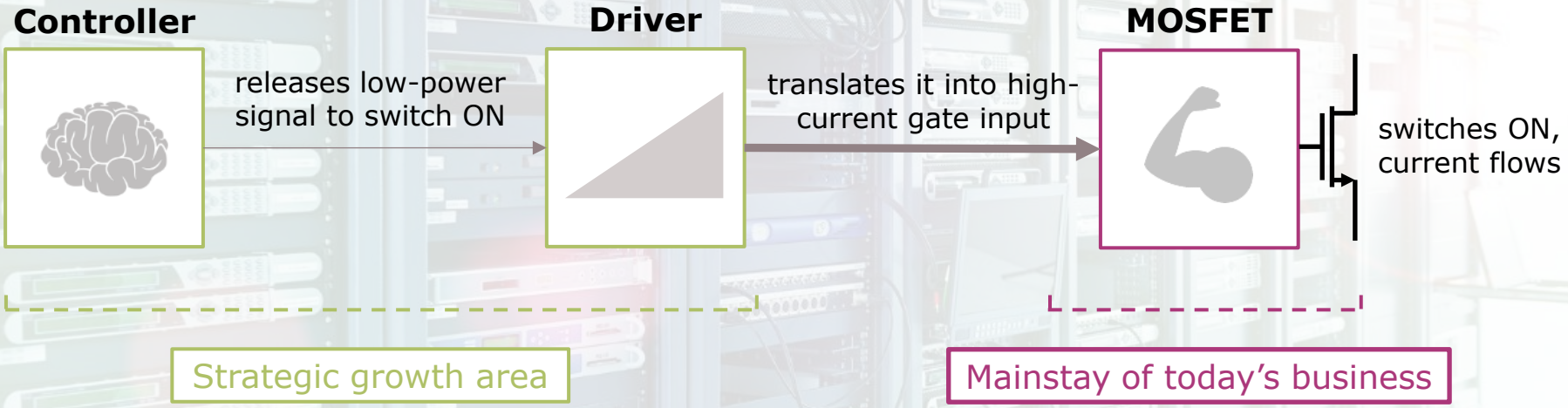
Communications

- Handsets
- Wearables
- Cellular infrastructure

AC-DC DC-DC RFS

Product-to-System approach opens growth opportunities beyond MOSFETs

Essential parts of any electronic system (e.g. in an SMPS); can be realized with separate components or as an integrated power stage as system-on-chip



Driving system approach creates opportunities for further growth

- Expansion of IC product portfolio increases addressable market
- TAM in 2021*: €7.0bn

- MOSFETs account for ~80% of today's PMM power business
- TAM in 2021*: €6.3bn

* Infineon estimates

Strengthening IC business allows for faster growth in power than market average






Average through-cycle growth of power business: 8% p.a.

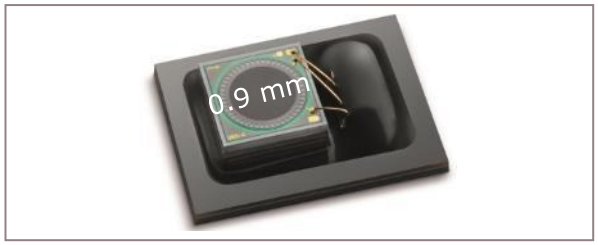
2-3%-pt p.a.	from power ICs	+	5-6%-pt p.a.	from MOSFETs

- Expand product portfolio
- Bundle with MOSFETs
- Tailor go-to-market strategy
- Leverage system knowhow

- Maintain technology leadership
- Capitalize on scale advantage
- Further extend market leadership

PMM is a leader in core technologies for ambient sensing, thus driving innovation

MEMS

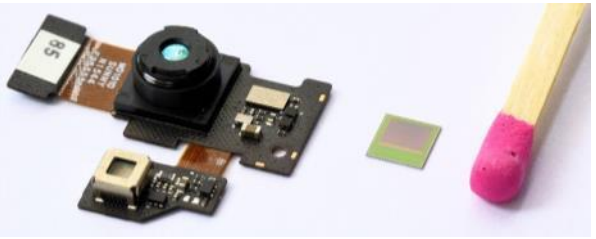


- #2 in the market (31.1%) for silicon microphones
- World's best signal-to-noise ratio
- Integration of additional sensing functions

Radar

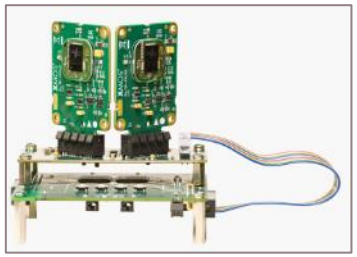
- 60 GHz radar sensors e.g. for gesture sensing (example: Google Soli)
- 24 GHz radar sensors e.g. for automotive, robotics and smart home

Time of Flight



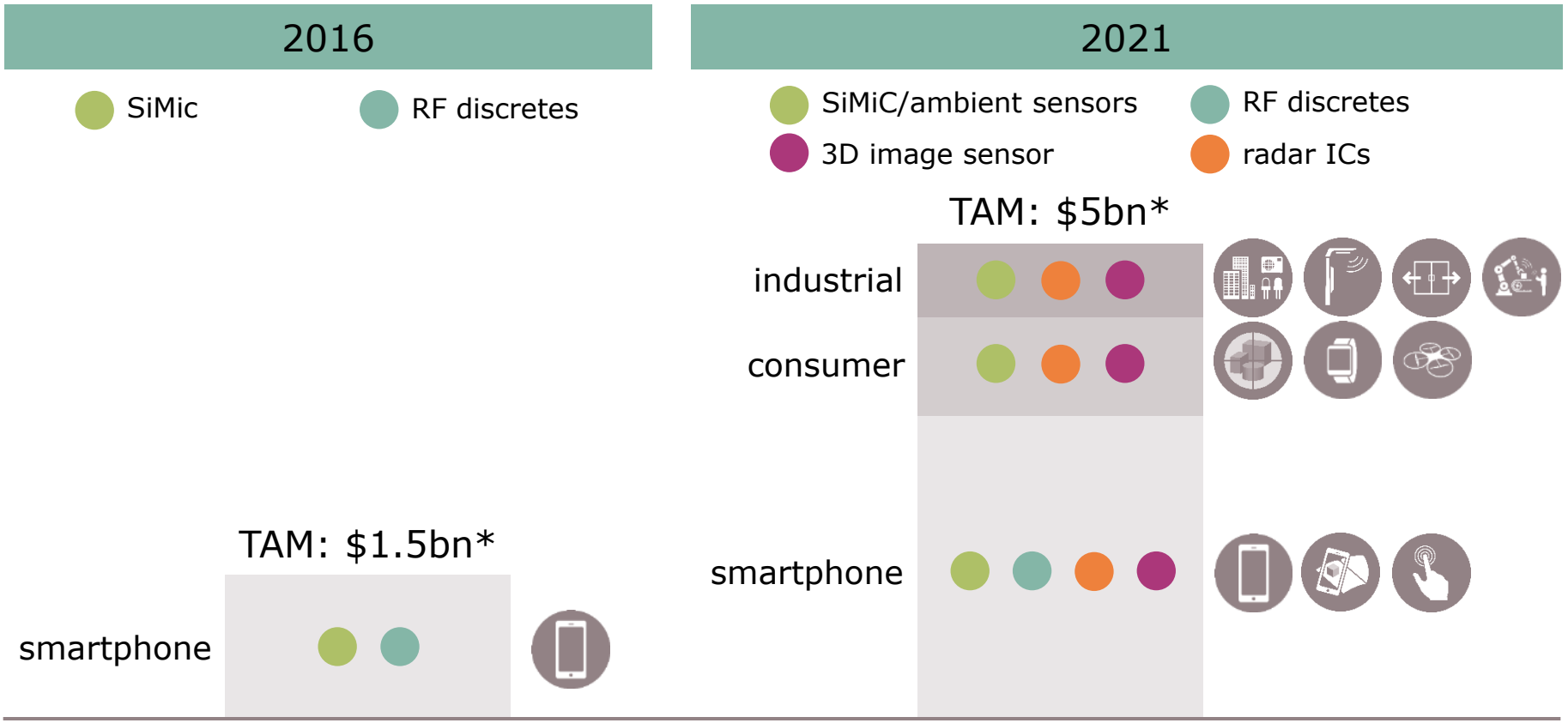
- REAL3™ image sensor for AR/VR applications in smartphones and automotive driver monitoring
- High-resolution 3D image sensor available with 19k, 38k and 100k pixels
- Measuring brightness and distance for every single pixel

Sensor fusion



- Combination of microphone and radar with audio processor from XMOS enables far field voice capture by audio beamforming combined with radar target presence detection.

Growth in RF & Sensing is driven by broader product portfolio and emerging applications



* Infineon estimates

- **SiMic:** Integrating additional ambient sensors in upcoming generations (e.g. temperature and pressure)
- **RF discretes:** Adding a focus on antenna-centric solutions to existing LNA and switch business

Tailored growth strategies help maintain leadership position in both major segments

Power

Current position

- Scale and technology leader in power MOSFETs
- Broadest portfolio: 25V – 900V
- Addressing all applications
- #1 holding ~1/3 of the market

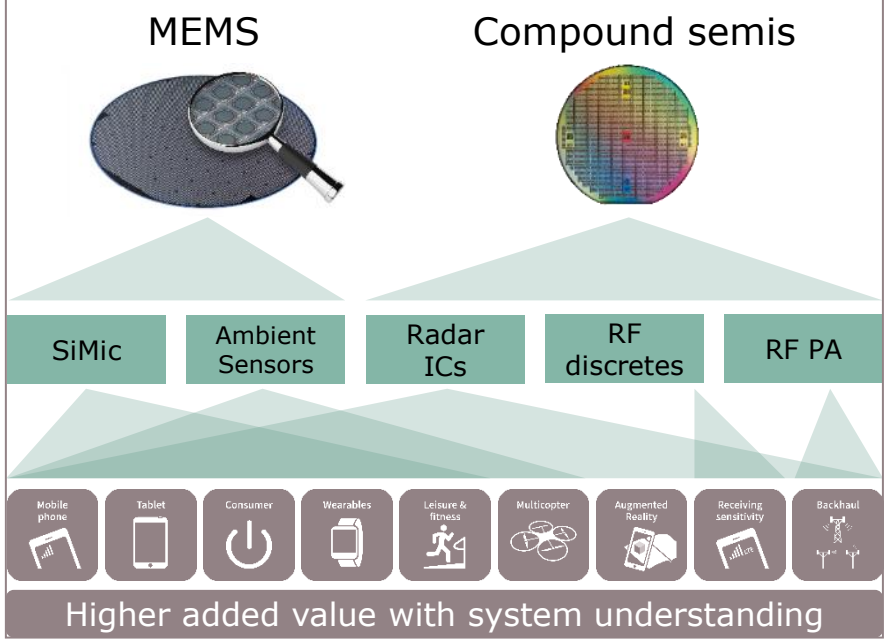
Growth levers

- Capitalize on scale and tech-nology leadership in discretes
- Double TAM by pushing into power management ICs

Growth of ~8% p.a.

RF & Sensing

Growth based on 3-layer-model



- Core **technologies** enable broad portfolio of **products** for even more **applications**.

Growth of ~8% p.a.

Infineon is the leader in security solutions for the connected world

- #1 in microcontroller-based smart card ICs*
- #1 in embedded digital security**
- Complete portfolio of hardware, software, services and turnkey solutions
- Leading in growth segments payment, government ID, connected car security, IoT, and Information and Communications Technology security

Infineon is ideally positioned to benefit from the growth trends in the security controller market

* Source: IHS Markit, Technology Group, "Smart Card Semiconductors Report", July 2017
** Source: IHS Markit, Technology Group, "Embedded Digital Security Report ", January 2016 (based on units, USD-ranking not provided)

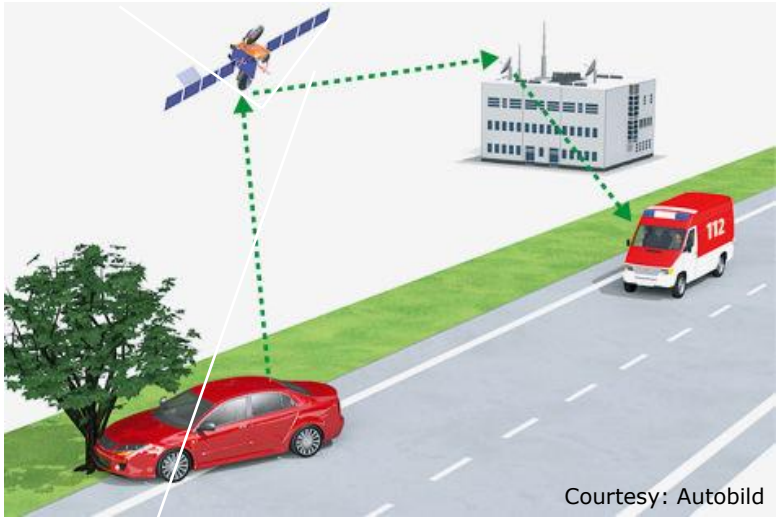
Tailored embedded security µC portfolio for applications in the hyper-connected IoT world

- Infineon AURIX™ microcontroller with HSM for onboard communication
- Security microcontrollers (e.g. eSIMs, TPMs) enable various functions like eCall, software over-the-air, vehicle-to-infrastructure, and on-board multimedia

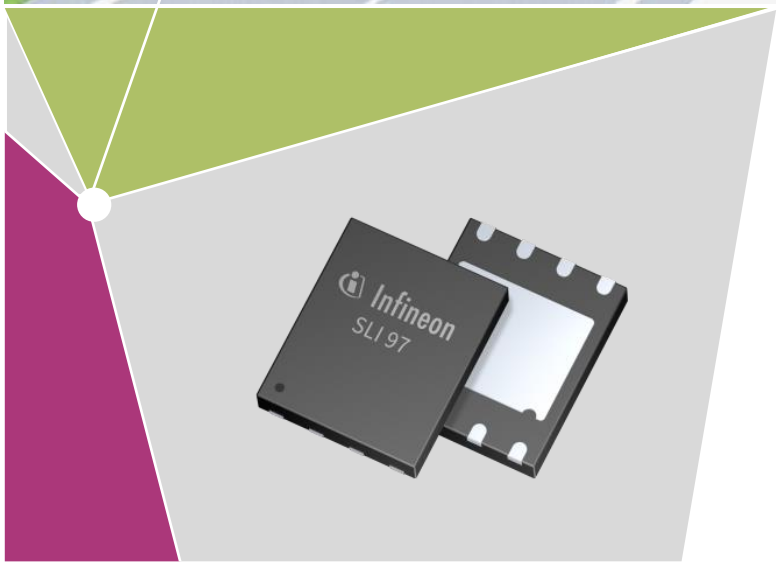
- Security microcontroller for Infineon MIPAQ™ Pro IPM enabling authentication
- Security chips are integrated in solutions for Industry 4.0 applications, e.g. robots

- OPTIGA™ TPM and OPTIGA™ Trust for devices like smart home routers and gateways (e.g. Google OnHub), smart meters, smart lighting etc.

Infineon is the leading supplier of eSIM for emergency call (eCall) system for cars



Courtesy: Autobild



eSIM

- Emergency call function (eCall) will be mandatory for all new registered cars in the EU as of 31 March 2018
- Infineon is world's leading supplier of embedded SIMs (eSIMs) used for eCall function
- In addition to eCall eSIMs enable various functions like
  - software over-the-air (SOTA)
  - vehicle-to-infrastructure
  - on-board multimedia
- Infineon's related eSIM revenue almost doubled in FY17; for FY18, again strong growth expected

Infineon's long-term growth is based on sustainable growth drivers

ATV	IPC	PMM	CCS
 Courtesy: Hyundai			
› CO_2 reduction › Advanced Driver Assistance Systems	› Energy efficiency › Automation › Productivity increase	› Energy efficiency › Power density › BLDC motors › Mobile device	› Security as a function › Mobile payments › Authentication › Internet of Things

~8% p.a. through-cycle growth

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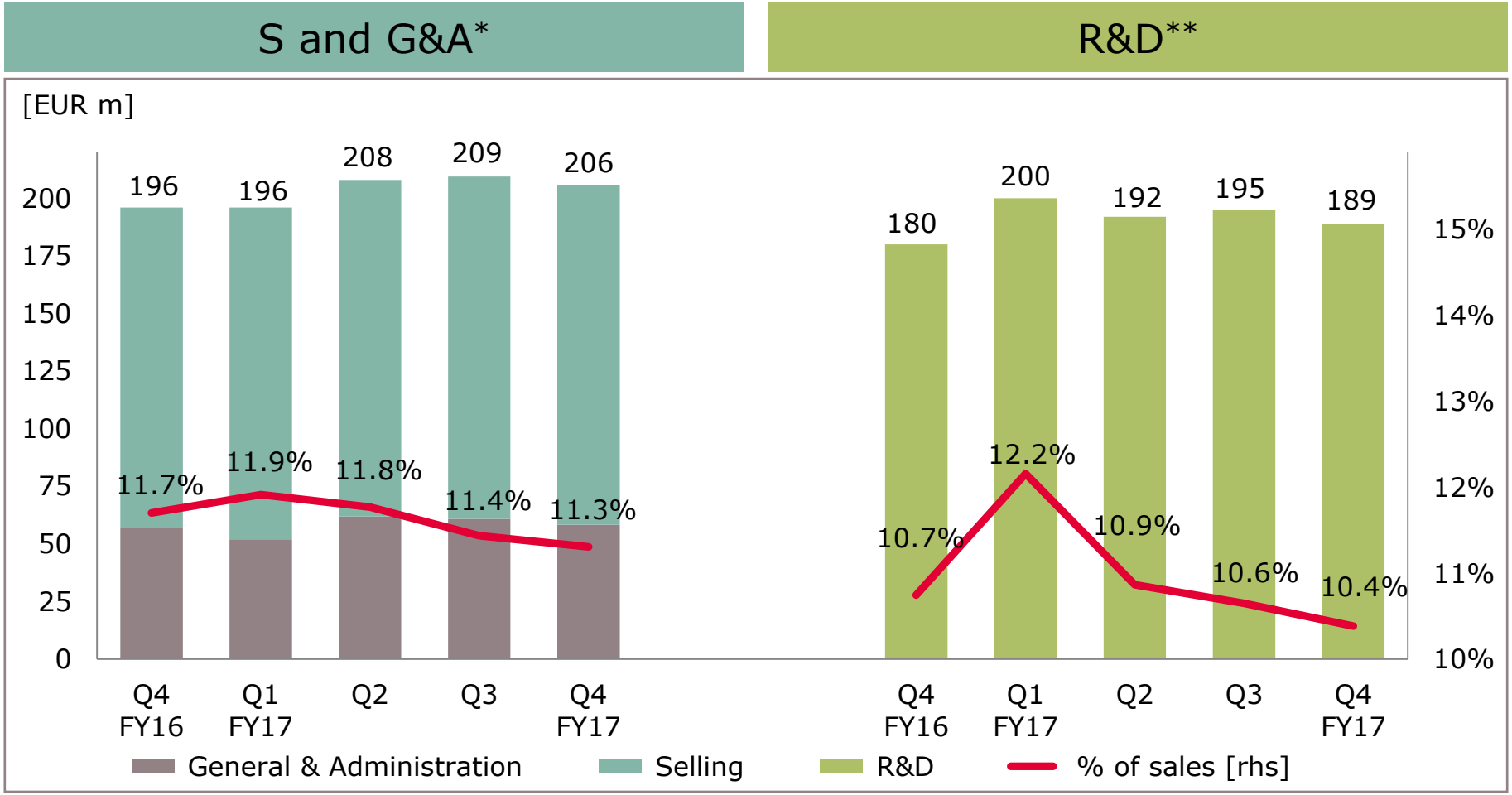
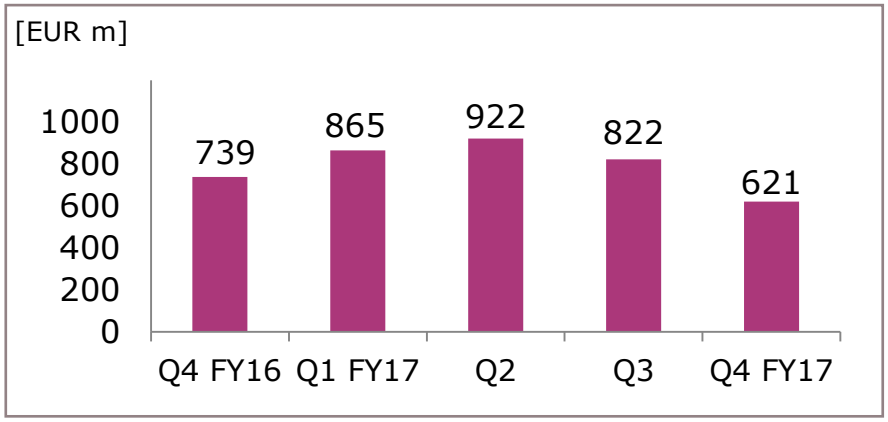
OPEX level right on target



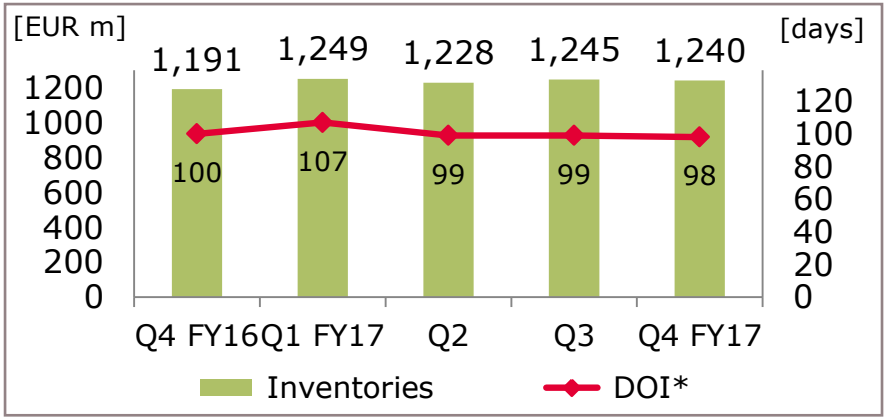
* Target range for SG&A: „Low teens percentage of sales".
** Target range for R&D: „Low to mid teens percentage of sales".

Increase in trade payables due to high investments

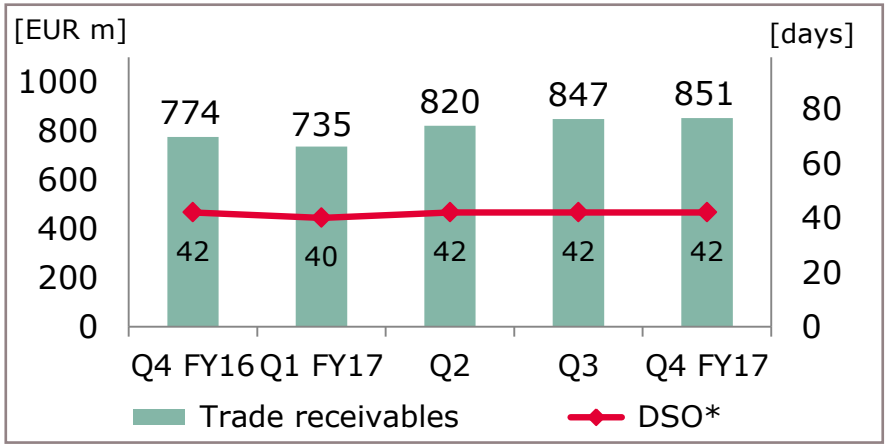
Working capital*



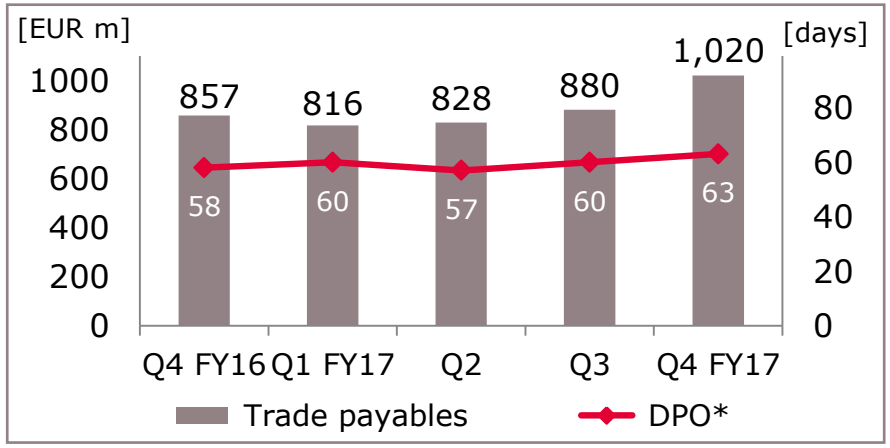
Inventories



Trade receivables

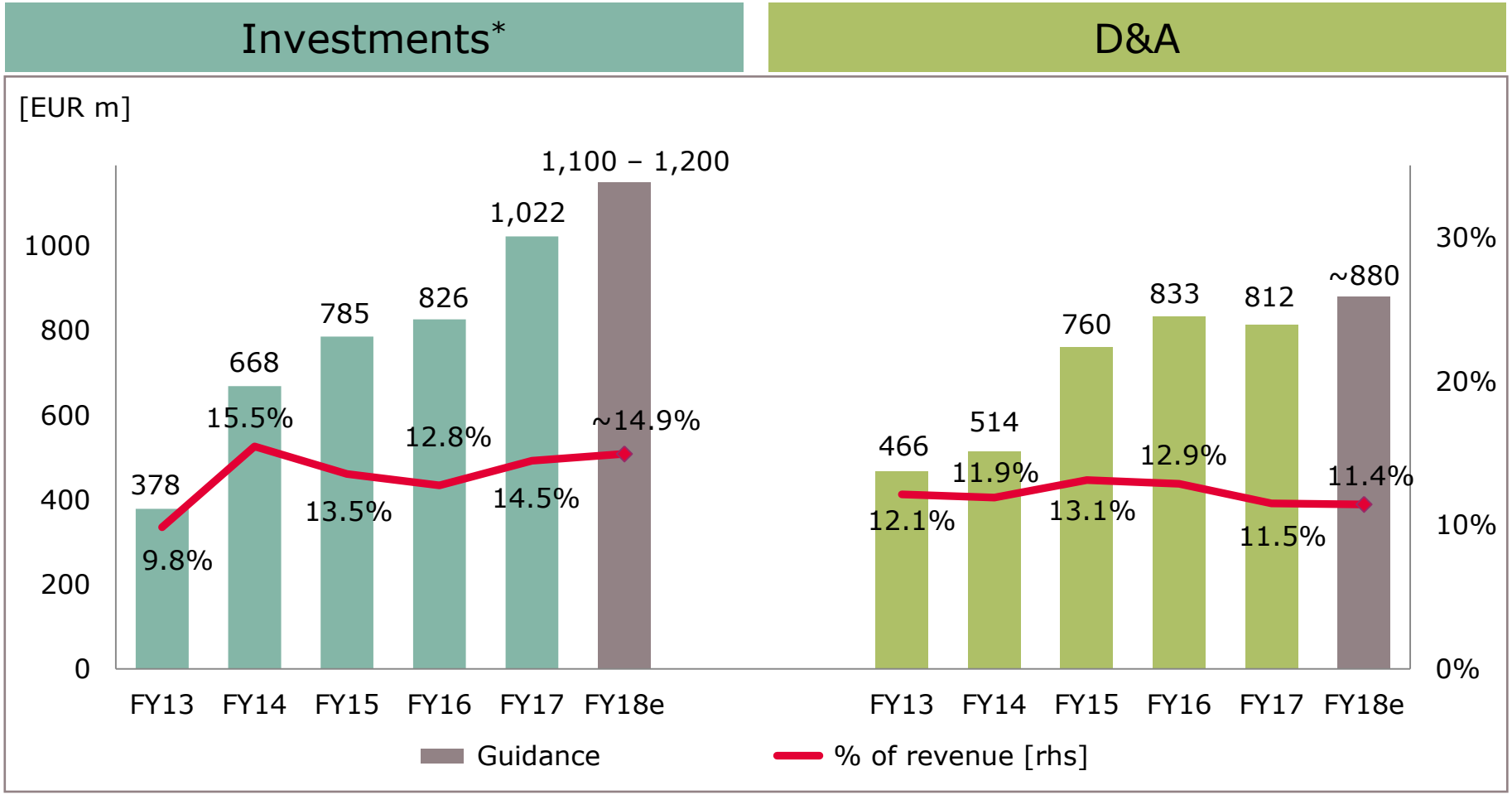


Trade payables



* For definition please see page "Notes".

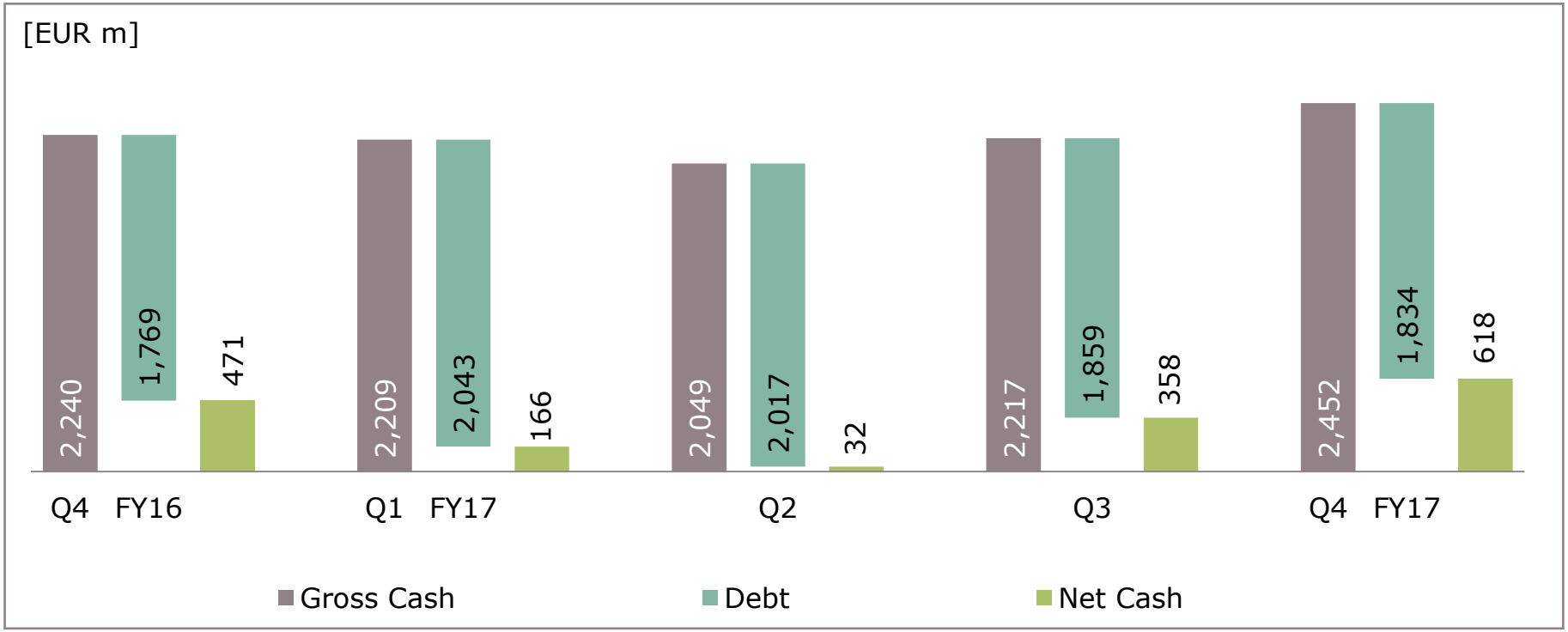
Investments between €1.1bn and €1.2bn due to strong underlying growth in demand



* For definition please see page „Notes".

Gross and Net Cash increased due to strong Free Cash Flow

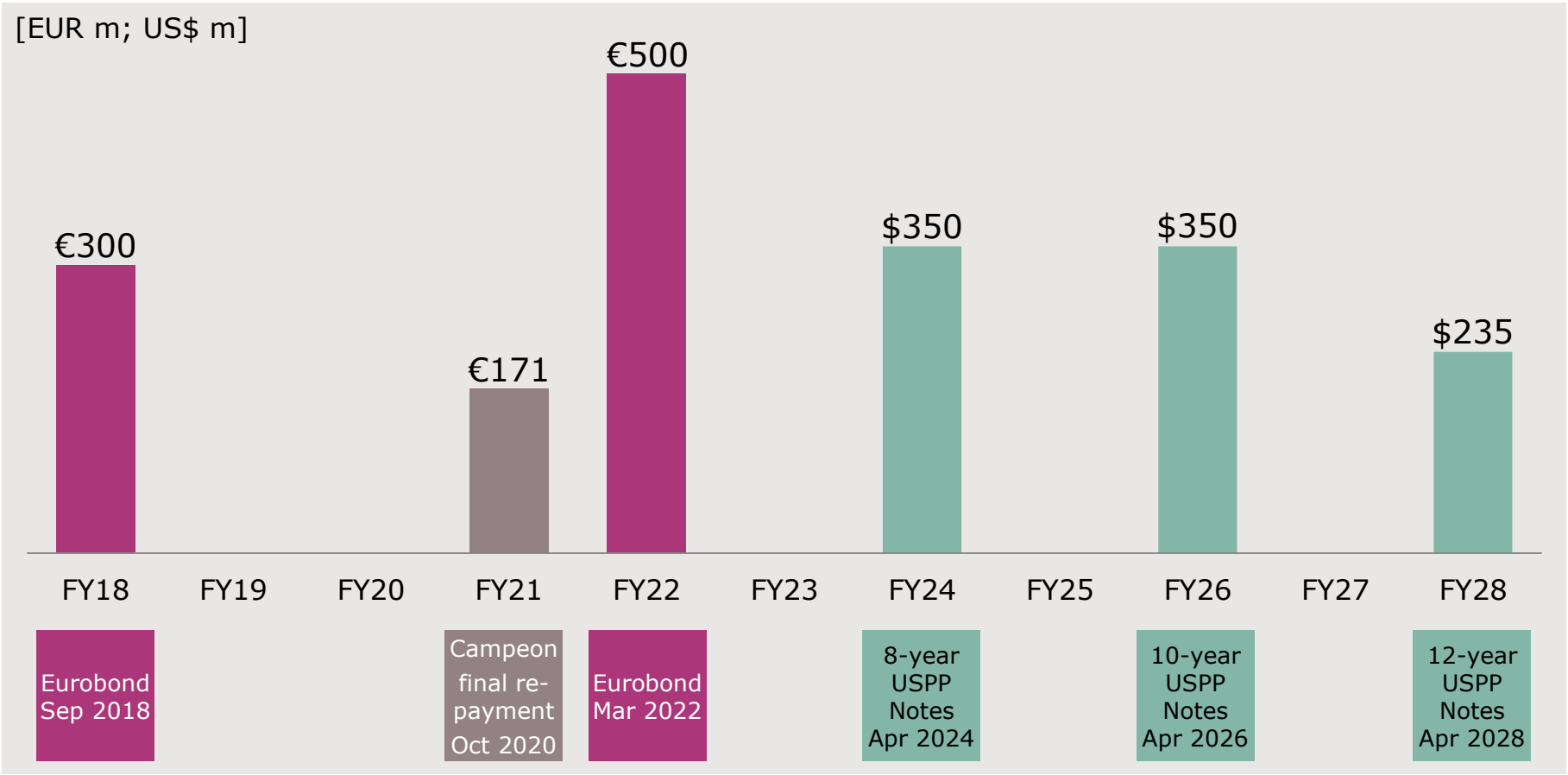
Liquidity development



- Free Cash Flow from continuing operations was €249m.
- Debt decreased by €25m due to change in FX-rates used for valuing US$-based debt.

Infineon has a balanced maturity profile and a solid investment grade rating (BBB) from S&P

Maturity profile



Note: Additional debt with maturities between 2017 and 2023 totaling €73m of which €38m repayments related to Campeon.

Part of your life. Part of tomorrow.

Infineon

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These statements are based on assumptions and projections resting upon currently available information and present estimates. They are subject to a multitude of uncertainties and risks. Actual business development may therefore differ materially from what has been expected.

Beyond disclosure requirements stipulated by law, Infineon does not undertake any obligation to update forward-looking statements.

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Infineon is a long-standing member of Europe's leading sustainability indices

Infineon's most recent achievements

MEMBER OF Dow Jones Sustainability Indices In Collaboration with RobecoSAM

- Jan 2017: Infineon is listed in the Sustainability Yearbook for the 7th consecutive year and, according to RobecoSAM, among the top 15% most sustainable companies worldwide
- Sep 2017: Infineon is listed in the Dow Jones Sustainability Europe Index (as the only semiconductor company) for the 8th consecutive year and in the World Index for the 3rd time

- Sep 2016: Infineon is listed in the STOXX® Global ESG Leaders Indices, which serves as an indicator of the quality of Infineon's performance in the governance, social and environmental areas (ESG)

Member 2016/2017 STOXX ESG LEADERS INDICES

FTSE4Good

- Infineon was added to the FTSE4Good Index Series in 2001 and has been confirmed as a member since then
- Jul 2017: Most recent review

- Dec 2016: In the Carbon Disclosure Project (CDP) climate change report, Infineon achieved a placing among the best companies in the Information Technology sector

CDP DRIVING SUSTAINABLE ECONOMIES

Included in ETHIBEL SUSTAINABILITY INDEX EXCELLENCE Europe

- Mar 2017: Infineon has been reconfirmed as a constituent of the Ethibel Sustainability Index (ESI) Excellence Europe

Financial calendar

Date	Location	Event
15 – 16 Nov 2017	Barcelona	Morgan Stanley TMT Conference
28 – 29 Nov 2017	Scottsdale, AZ	Credit Suisse TMT Conference
09 – 10 Jan 2018	New York	Commerzbank German Investment Seminar
31 Jan 2018*		Q1 FY18 Results
22 Feb 2018	Munich	Annual General Meeting
26 – 28 Feb 2018	Barcelona	Mobile World Congress
03 May 2018*		Q2 FY18 Results
12 June 2018	London	Capital Markets Day "IFX Day 2018"
01 Aug 2018*		Q3 FY18 Results
12 Nov 2018*		Q4 FY18 and FY 2018 Results

* preliminary

Notes

Investments =
'Purchase of property, plant and equipment'
+ 'Purchase of intangible assets and other assets' *incl. capitalization of R&D expenses*

Capital Employed =
'Total assets'
– 'Cash and cash equivalents'
– 'Financial investments'
– 'Assets classified as held for sale'
– ('Total Current liabilities'
– 'Short-term debt and current maturities of long-term debt'
– 'Liabilities classified as held for sale')

Please note:
All positions in ' ' refer to the respective accounting position and therefore should be applied with the positive or negative sign used in the relevant accounting table.

RoCE =
NOPAT / Capital Employed =
('Income from continuing operations'
– 'financial income'
– 'financial expense')
/ Capital Employed

Working Capital =
('Total current assets'
– 'Cash and cash equivalents'
– 'Financial investment'
– 'Assets classified as held for sale')
– ('Total current liabilities'
– 'Short term debt and current maturities of long-term debt'
– 'Liabilities classified as held for sale')

DOI (days of inventory; quarter-to-date) =
('Net Inventories' / 'Cost of goods sold') * 90

DSO (days sales outstanding; quarter-to-date) =
('Trade receivables' / 'revenue') * 90

DPO (days payables outstanding; quarter-to-date) =
('Trade payables' / ['Cost of goods sold' + 'Purchase of property, plant and equipment']) * 90

Glossary

AD	automated driving
ADAS	advanced driver assistance system
AEB	automatic emergency braking
BoM	bill of material
DPM	digital power management
eCall	emergency call
EPS	electric power steering
eSIM	embedded subscriber identity module
EV	electric vehicle
HEV	mild and full hybrid electric vehicle
HSM	hardware security module
ICE	internal combustion engine
IPM	intelligent power module

MHA	major home appliances
micro-hybrid	vehicles using start-stop systems and limited recuperation
mild-hybrid	vehicles using start-stop systems, recuperation, DC-DC conversion, e-motor
OBC	onboard charger
PHEV	plug-in hybrid electric vehicle
SiC	silicon carbide
SiGe	silicon germanium
SOTA	software over-the-air
TPM	trusted platform module
UPS	uninterruptible power supply
V2X	vehicle-to-everything communication
VSD	variable speed drive
xEV	all degrees of vehicle electrification (EV, HEV, PHEV)

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